

# CMD12P10S-VB Datasheet P-Channel 100 V (D-S) MOSFET

PRODUCT	SUMMARY		
V <sub>DS</sub> (V)	$R_{DS(on)}(\Omega)$	I <sub>D</sub> (A)	Q <sub>g</sub> (Typ.)
- 100	$0.250 \text{ at V}_{GS} = -10 \text{ V}$	- 8.8	11.7
- 100	0.280 at V <sub>GS</sub> = - 4.5 V	- 8.0	11.7

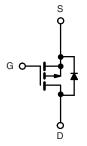
#### **FEATURES**

- Halogen-free According to IEC 61249-2-21 Definition
- Trench Power MOSFET
- 100 % R<sub>g</sub> and UIS Tested
  Compliant to RoHS Directive 2002/95/EC



#### **APPLICATIONS**

- Power Switch
- DC/DC Converters



P-Channel MOSFET

TO-252	
<u>ر</u>	
<u> </u>	
	Drain Connected to Tab
G D S	
Top View	

ABSOLUTE MAXIMUM RATINGS	$T_C = 25  ^{\circ}C$ , unless othe	rwise noted			
Parameter		Symbol	Limit	Unit	
Drain-Source Voltage	V <sub>DS</sub>	- 100	V		
Gate-Source Voltage		V <sub>GS</sub>	± 20	V	
Continuous Drain Current (T <sub>.1</sub> = 150 °C)	T <sub>C</sub> = 25 °C	,	- 8.8	A	
Continuous Diain Current (1) = 130 °C)	T <sub>C</sub> = 70 °C	I <sub>D</sub>	- 7.1		
Pulsed Drain Current		I <sub>DM</sub>	- 25	A	
Avalanche Current		I <sub>AS</sub>	- 18		
Single Avalanche Energy <sup>a</sup>	L = 0.1 mH	E <sub>AS</sub>	16.2	mJ	
	T <sub>C</sub> = 25 °C	Б	32.1 <sup>b</sup>	147	
Maximum Power Dissipation <sup>a</sup>	T <sub>A</sub> = 25 °C <sup>c</sup>	- P <sub>D</sub>	2.5	W	
Operating Junction and Storage Temperature Ra	ange	T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150	°C	

THERMAL RESISTANCE RATINGS				
Parameter	Symbol	Limit	Unit	
Junction-to-Ambient (PCB Mount) <sup>c</sup>	R <sub>thJA</sub>	50	°C/W	
Junction-to-Case (Drain)	R <sub>thJC</sub>	3.9	C/VV	

#### Notes:

- a. Duty cycle  $\leq$  1 %.
- b. See SOA curve for voltage derating.
- c. When Mounted on 1" square PCB (FR-4 material).

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Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{DS} = 0 \text{ V}, I_{D} = -250 \mu\text{A}$	- 100			V	
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	- 1		- 2.5	٧	
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 250	nA	
		V <sub>DS</sub> = - 100 V, V <sub>GS</sub> = 0 V			- 1		
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = - 100 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C			- 50	μΑ	
		V <sub>DS</sub> = - 100 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 150 °C			- 250		
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \le -10 \text{ V}, V_{GS} = -10 \text{ V}$	- 15			Α	
	Ь	V <sub>GS</sub> = - 10 V, I <sub>D</sub> = - 3.6 A		0.250			
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = - 4.5 V, I <sub>D</sub> = - 3.4 A		0.280		Ω	
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = - 15 V, I <sub>D</sub> = - 3.6 A		12		S	
Dynamic <sup>b</sup>				•			
Input Capacitance	C <sub>iss</sub>			1055		pF	
Output Capacitance	C <sub>oss</sub>	V <sub>GS</sub> = 0 V, V <sub>DS</sub> = - 50 V, f = 1 MHz		65			
Reverse Transfer Capacitance	C <sub>rss</sub>			41			
Total Ooks Observed		V <sub>DS</sub> = - 50 V, V <sub>GS</sub> = - 10 V, I <sub>D</sub> = - 3.6 A		23.2	34.8		
Total Gate Charge <sup>c</sup>	Qg	V <sub>DS</sub> = - 50 V, V <sub>GS</sub> = - 4.5 V, I <sub>D</sub> = - 3.6 A		11.7	17.6	nC	
Gate-Source Charge <sup>c</sup>	$Q_{gs}$			3.5			
Gate-Drain Charge <sup>c</sup>	$Q_{gd}$			4.8			
Gate Resistance	$R_g$	f = 1 MHz	1.2	5.7	11.5	Ω	
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>			7	14		
Rise Time <sup>c</sup>	t <sub>r</sub>	$V_{DD} = -50 \text{ V}, R_L = 17.2 \Omega$		12	18		
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>	$I_D \cong$ - 2.9 A, $V_{GEN}$ = - 10 V, $R_g$ = 1 $\Omega$		33	50	ns	
Fall Time <sup>c</sup>	t <sub>f</sub>	1		9	18	1	
Drain-Source Body Diode Ratings ar	nd Characteri	stics T <sub>C</sub> = 25 °C <sup>b</sup>					
Continuous Current	I <sub>S</sub>				- 8.8		
Pulsed Current	I <sub>SM</sub>				- 15	Α	
Forward Voltage <sup>a</sup>	V <sub>SD</sub>	I <sub>F</sub> = - 2.9 A, V <sub>GS</sub> = 0 V		- 0.8	- 1.5	V	
Reverse Recovery Time	t <sub>rr</sub>			50	75	ns	
Peak Reverse Recovery Current	I <sub>RM(REC)</sub>	I <sub>F</sub> = - 2.9 A, dl/dt = 100 A/μs		- 4	- 6	Α	
Reverse Recovery Charge	Q <sub>rr</sub>	† †		98	147	nC	

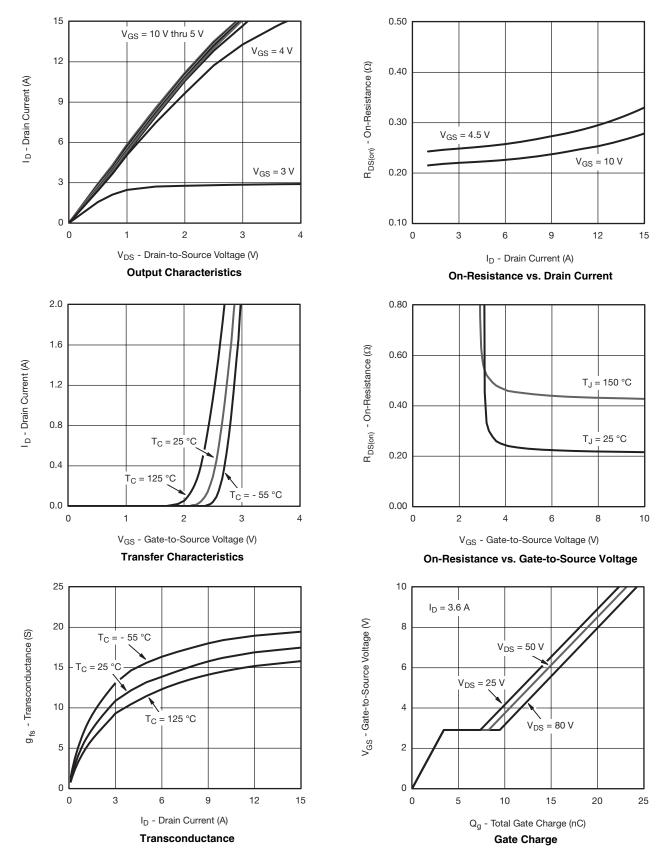
#### Notes:

- a. Pulse test; pulse width  $\leq$  300  $\mu s,$  duty cycle  $\leq$  2 %.
- b. Guaranteed by design, not subject to production testing.c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

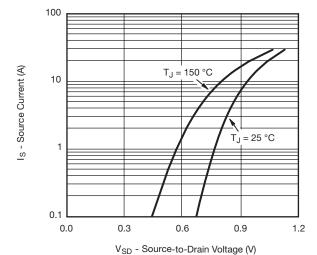


#### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

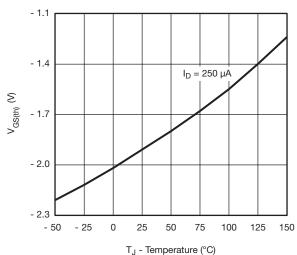




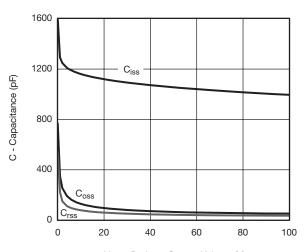
### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



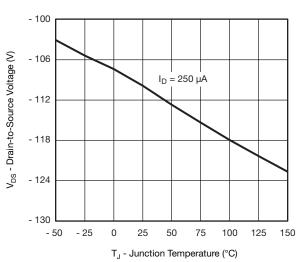
Source-Drain Diode Forward Voltage



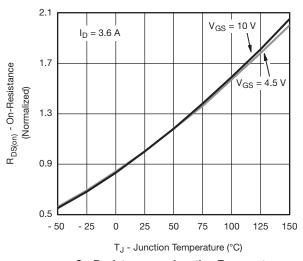
Threshold Voltage



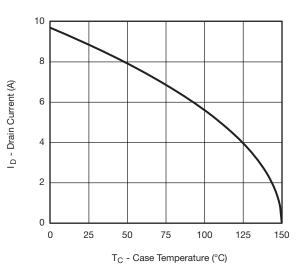
 $V_{DS}$  - Drain-to-Source Voltage (V)  $\label{eq:capacitance}$ 



**Drain Source Breakdown vs. Junction Temperature** 



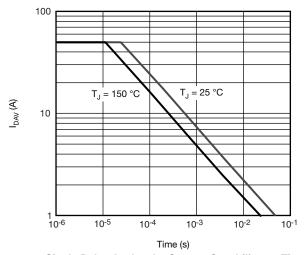
On-Resistance vs. Junction Temperature

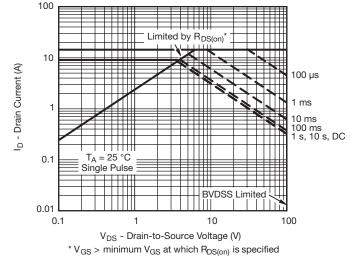


**Current Derating** 



### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

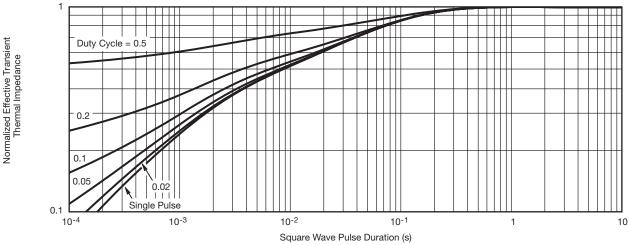




Single Pulse Avalanche Current Capability vs. Time



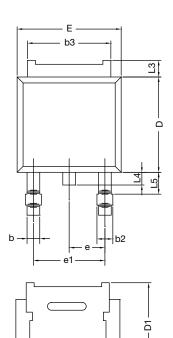


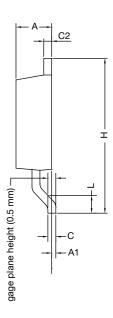


Normalized Thermal Transient Impedance, Junction-to-Case



# **TO-252AA Case Outline**





	MILLIN	METERS	INC	HES	
DIM.	MIN.	MAX.	MIN.	MAX.	
А	2.18	2.38	0.086	0.094	
A1	-	0.127	-	0.005	
b	0.64	0.88	0.025	0.035	
b2	0.76	1.14	0.030	0.045	
b3	4.95	5.46	0.195	0.215	
С	0.46	0.61	0.018	0.024	
C2	0.46	0.89	0.018	0.035	
D	5.97	6.22	0.235	0.245	
D1	4.10	-	0.161	-	
E	6.35	6.73	0.250	0.265	
E1	4.32	-	0.170	-	
Н	9.40	10.41	0.370	0.410	
е	2.28	BSC	0.090	BSC	
e1	4.56	4.56 BSC		BSC	
L	1.40	1.78	0.055	0.070	
L3	0.89	1.27	0.035	0.050	
L4	-	1.02	-	0.040	
L5	1.01	1.52	0.040	0.060	
ECN: T16-0236-Rev. P, 16-May-16					

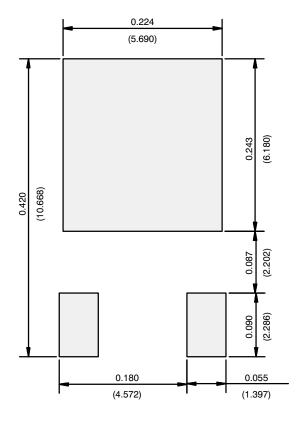
ECN: T16-0236-Rev. P, 16-May-16 DWG: 5347

## Notes

• Dimension L3 is for reference only.



### **RECOMMENDED MINIMUM PADS FOR DPAK (TO-252)**



Recommended Minimum Pads Dimensions in Inches/(mm)

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